

Abstract of the Disclosure

In the flip-chip BGA semiconductor device of the present invention, a stiffener is bonded by means of adhesive on the surface of a substrate on which a semiconductor chip is mounted in the area surrounding the semiconductor
5 chip, and gaps are provided between the substrate and the stiffener that each extend outwardly from positions that confront opposite sides of the semiconductor chip and that communicate with the ends of the substrate. These gaps can be formed by depressions that are provided in the substrate or in the stiffener.